



NOTES:

1. MATERIAL SPECIFICATION

- 1) INSULATION MATERIAL THERMOPLASTIC.
- 2) SHELL: SPCC/COPPER ALLOY ; T: 0.30mm
PLATING: NICKEL
- 3) TERMINAL: COPPER ALLOY, T: 0.25mm
PLATING: GOLD/TIN PLATED.

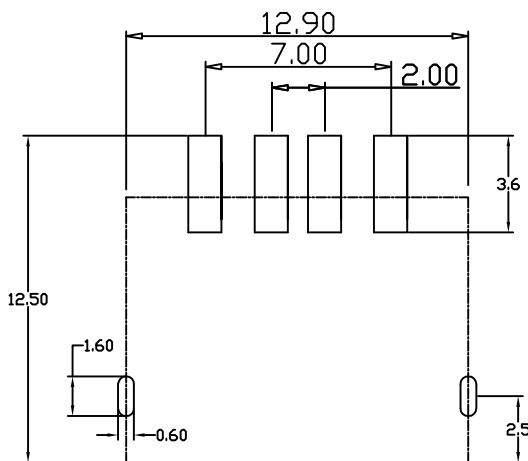
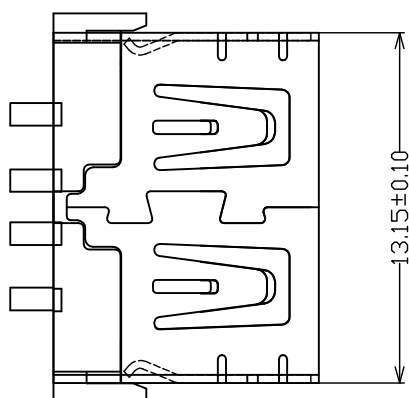
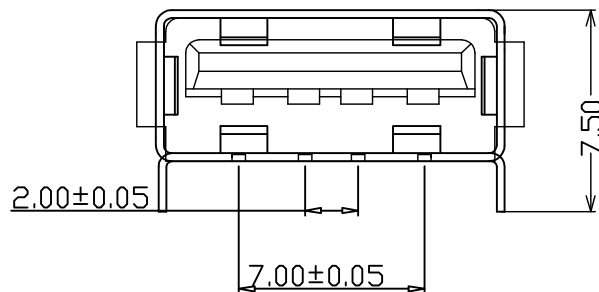
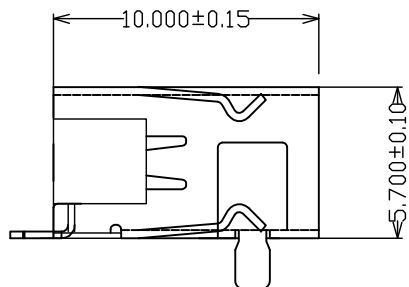
2. ELECTRICAL CHARACTERISTIC:

- 1) INSULATION RESISTANCE: 1000MΩ MIN.
- 2) CONTACT RESISTANCE: 30mΩ MAX.
- 3) WITHSTANDING VOLTAGE: 500V AC.

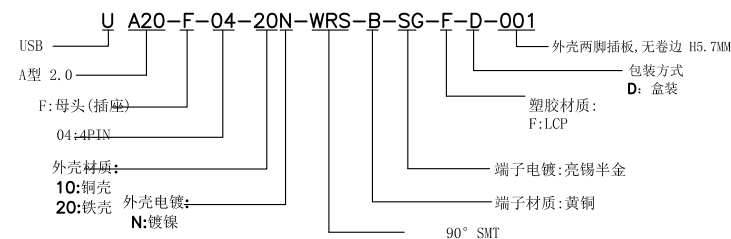
3. MECHANICAL CHARACTERISTICS:

- 1) INSERTION FORCE: 3.57Kgf MAX.
- 2) EXTRACTION FORCE: 1.02Kgf MIN.

ORDERING INFORMATION



RECOMMENDED P. C. B. LAYOUT



TOLERANCE UNLESS OTHERWISE SPECIFIED		BZOOC 东莞市柏洲电子有限公司 Dongguan BzooC Electronics, Ltd	
.X± 0.35	X.*± 1.5*	APR. AX.T	TITLE: USB A/F 短体10MM 90° SMT H=5.7MM 外壳两脚插板 无卷边
.XX± 0.25	.X*± 1.0*	CHK. Y.L	PART NO.
.XXX± 0.15	.XX*± 0.5*	DRA. Y.L	PROJ. UNITS. MM SCALE: 1:1 SHEET. 1/1
CUSTOMER DRAWING			

A0	FIRST RELEASE	Y.L	2019.06.21
REV.	ECN. NO.	APR.	DATE